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Dated: April 8, 2002

Signature: *Lawrence E. Russ*

(Lawrence E. Russ)

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Docket No.: INTECH 3.0-038
99P7451US
(PATENT)



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
J. Mandelman et al.

Application No.: 09/245,269

Group Art Unit: 2814

Filed: February 5, 1999

Examiner: D. Nguyen

For: FIELD-SHIELD-TRENCH ISOLATION FOR
GIGABIT DRAMS

Commissioner for Patents
Washington, DC 20231

AMENDMENT

Dear Sir:

Responsive to the Office Action dated December 7, 2001, please amend the above-identified application as follows:

IN THE CLAIMS

CLEAN COPY OF AMENDED CLAIM:

1. (Amended) A semiconductor body containing a semiconductor structure and comprising:

AI
cont

the semiconductor body defining an isolation trench having a bottom and sidewalls and having an upper portion and a lower portion, said isolation trench enclosing an area of the semiconductor body which contains a semiconductor structure which is to be electrically isolated from other semiconductor structures that are also contained within the semiconductor body but which are not located within the enclosed area;

the lower portion of the isolation trench being at least partly filled with an electrically conductive material that has sidewall portions which are at least partly separate from the sidewalls of the lower portion of the isolation trench by a first electrical insulator, said

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